



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:)	Group Art Unit: 2827
Michael John Watson)	
Serial Number 09/954,528)	
Filed: September 17, 2001)	Examiner: Chambliss
Title: IMPROVED ADHESIVES FOR SEMICONDUCTOR APPLICA- TIONS EFFICIENT PROCESSES)	
FOR PRODUCING SUCH)	AMENDMENTS TO
DEVICES AND THE DEVICE)	THE ABSTRACT
PER SE PRODUCED BY THE)	
EFFICIENT PROCESSES)	
Attorney Docket: DC - 4952)	April 28, 2003

Assistant Commissioner
For Patents
Washington DC 20231

Dear Sir:

Please find enclosed a new page setting forth the amended ABSTRACT.

Respectfully submitted,

A handwritten signature in black ink that appears to read "Robert L. McKellar".

Robert L. McKellar
Reg. No. 26,002
(989) 631-4551



ABSTRACT

Die attach adhesives and methods for their use, along with the devices that are obtained by the use of the methods. Using semiconductor chips as an example, the
5 adhesives and the method for using them provides an interface between a chip (die) and the chip support. The method includes creating a space between the chip and the chip support of a given sized opening by using inorganic insulator particles having an average particle size of 1 μm to 1000 μm and a major axis to minor axis ratio of about 1.0 to 1.5.

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